

**IN THE SPECIFICATION**

Please replace the paragraph beginning on page 12, line 25 with the following rewritten paragraph:

--Techniques for forming nanotube field emitter structures, with both oriented and non-oriented nanotubes structures are also described in Patent Nos. or applications serial nos. 09/236966 6,250,984, 09/236933, 6,283,812, 09/296572 6,630,772, 09/351537, 09/512873, and 09/376457 6,277,318, the disclosures of which are incorporated by reference.--

Please replace the paragraph beginning on page 13, line 13 with the following rewritten paragraph:

--As reflected in these techniques, it is possible to form carbon nanotube emitters on a substrate by either in-situ growth or post-deposition spraying techniques. For in-situ growth in the invention, the device substrate, with mask in place over the components other than the cathode electrode surface, is generally placed in a chemical vapor deposition chamber, and pre-coated with a thin layer (e.g., 1-20 nm thick) of catalyst metal such as Co, Ni or Fe (or formed from such a metal). The gas chemistry is typically hydrocarbon or carbon dioxide mixed with hydrogen or ammonia. Depending on specific process conditions, it is possible to grow the nanotubes in either an aligned or random manner. Optionally, a plasma enhanced chemical vapor deposition technique is used to grow highly aligned nanotubes on the substrate surface, as disclosed in co-assigned patent ~~application serial no. 09/376457, supra~~ no. 6,277,318. Other techniques are also possible.--

Please replace the paragraph beginning on page 13, line 17 with the following paragraph:

--In a typical post-deposition technique, reflected, for example, in patent ~~application serial no. 09/296572, supra,~~ no. 6,630,772 pre-formed and purified nanotube powders are mixed

with solvents and optionally binders (which are pyrolyzed later) to form a solution or slurry. The mixture is then disposed, e.g., dispersed by spray, onto the masked device substrate in which the cathode electrode surface is exposed. The cathode electrode optionally is provided with a layer of a carbon dissolving element (e.g., Ni, Fe, Co) or a carbide forming element (e.g., Si, Mo, Ti, Ta, Cr), to form a desired emitter structure. Annealing in either air, vacuum or inert atmosphere is followed to drive out the solvent, leaving a nanotube emitter structure on the substrate. And where the carbon dissolving or carbide forming elements are present, annealing promotes improved adhesion. Other post-deposition techniques are also possible.--